

#### 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# PCN#20200904000.1 Qualification of HFTF as an additional assembly site for select Devices Change Notification / Sample Request

Date: September 09, 2020

To: AVNET PCN

#### Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN\_ww\_admin\_team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

#### 20200904000.1 Attachment: 1

#### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

| DEVICE           | <b>CUSTOMER PART NUMBER</b> |
|------------------|-----------------------------|
| SN74LVC1G125DBVR | null                        |
| SN74LVC1G125DBVT | null                        |
| SN74LVC2G125DCUR | null                        |
| SN74LVC2G125DCUT | null                        |
| SN74LVC1G07DCKR  | null                        |
| SN74LVC1G04DCKR  | null                        |
| SN74LVC1G06DCKR  | null                        |
| SN74LVC1G123DCUR | null                        |
| SN74LVC2G132DCUR | null                        |

Technical details of this Product Change follow on the next page(s).

|   |   | 1             |        |        |                |         |             |                                     |                 |          |                  |                                 |
|---|---|---------------|--------|--------|----------------|---------|-------------|-------------------------------------|-----------------|----------|------------------|---------------------------------|
| PCN   | Number:   | 20200904000.1 |        |        |                |         |             | PCN Date:                           |                 |          | Sept 09, 2020    |                                 |
| Title: Qualification of HFTF as an additional assembly site for select Devices  |   |               |        |        |                |         | 5           |                                     |                 |          |                  |                                 |
| Cust  | Customer Contact: PCN Manager Dept: Quality Services  |               |        |        |                |         |             |                                     |                 |          |                  |                                 |
| Prop  | oosed 1 <sup>st</sup> Sh  | ip Da         | ite:   | Dec 0  | 9, 2           | 2020    |             | Estim                               |                 |          | Sample lability: | Date provided at sample request |
| Change Type:  |   |               |        |        |                |         |             |                                     |                 |          |                  |                                 |
| $\boxtimes$   | Assembly Sit  | e             |        |        |                | Design  | 1           |                                     |                 |          | Wafer B          | ump Site                        |
|   | Assembly Pro  | cess          |        |        |                | Data S  | Sheet       |                                     |                 |          |                  | ump Material                    |
| $\boxtimes$   | Assembly Ma   | terial        | S      |        |                | Part nu | umber (     | change                              | Wafer           |          |                  | ump Process                     |
|   | Mechanical S  |               |        |        |                | Test Si |             |                                     |                 |          |                  | ab Site                         |
| $\boxtimes$   | Packing/Ship  | ping/         | Labeli | ing    |                | Test Pr | rocess      |                                     |                 |          | Wafer F          | ab Materials                    |
|   |   |               |        |        |                |         |             |                                     |                 |          | Wafer F          | ab Process                      |
|   |   |               |        |        |                | PCN     | <b>Deta</b> | ils 💮                               |                 |          |                  |                                 |
| Des   | cription of C   | hang          | je:    |        |                |         |             |                                     |                 |          |                  |                                 |
| asse  | mbly sites are  | e as f        | ollows | S:     |                |         |             | A C                                 |                 | <u> </u> | .5               | rences and current              |
|   |   |               |        | SEWH   |                |         | HIT         |                                     |                 | NA       |                  | HFTF                            |
| Moi   | unt Compoun   | d             | 112    | 20999A | 2              |         | RZ2410      |                                     | 400             | 018      | 30               | SID# A-18                       |
| Mol   | d Compound  |               | 40     | 20039A | 1              | F       | RM500F      | 5                                   | 450179          |          | 79               | SID#R-31                        |
| Lea   | d Finish  |               | _ N    | NiPdAu |                | M       | 1atte Si    | n l                                 | NiPdAu          |          | ıu               | Matte Sn                        |
| Wir   | e type  |               |        | Au     |                |         | Au          |                                     | Au              |          |                  | Cu                              |
| for t<br>and<br>G4 s<br>Exar  | Upon expiry of this PCN TI will combine lead free solutions in a single standard part number, for the devices in group 2. For example; SN74LVC1G04DCKR – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. SN74LVC1G04DCKRG4."  Example:  - Customer order for 7500 units of SN74LVC1G04DCKR with 2500 units SPQ (Standard Pack Quantity per Reel).  - TI can satisfy the above order in one of the following ways.  I. 3 Reels of NiPdAu finish.  II. 3 Reels of Matte Sn finish  III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.  IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. |               |        |        |                |         |             | n both Matte Sn<br>he part with the |                 |          |                  |                                 |
|   | son for Char  | ige:          |        |        |                |         |             |                                     |                 |          |                  |                                 |
|   | oly continuity  |               |        |        | _              |         |             |                                     |                 |          |                  |                                 |
|   | Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):  |               |        |        |                |         |             |                                     | re / negative): |          |                  |                                 |
| None  |   |               |        |        | _              |         |             |                                     |                 |          |                  |                                 |
| Anti  | cipated imp   |               |        |        |                |         |             | 0 0 N D                             | -t ^            | ٠ ١      | tont ::-:        | uho puo duiviere fire           |
| No Impact to the Material Declaration Product Content reports are drived production data and will be available following the product release. Upon production release the revised reports can obtained at the site link below |   |               |        |        | the production |         |             |                                     |                 |          |                  |                                 |

# Changes to product identification resulting from this PCN:

| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City |
|---------------|----------------------------|-----------------------------|---------------|
| ASEWH         | AWH                        | CHN                         | Weihai        |
| HIT           | HTC                        | JPN                         | Kitatsugaru   |
| HNA           | HNT                        | THA                         | Ayutthaya     |
| HFTF          | HFT                        | CHN                         | Hefei         |

Sample product shipping label (not actual product label)

G4: NiPdAu G3: Matte Sn



MADE IN: Malaysia 2DC: 2Q:

MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT:

LBL: 5A (L)TO:1750



(1P) SN74LS07NSR

(Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483S12

(2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA 23L) ACO: MYS

# **Product Affected:**

| SN74LVC1G04DCKR | SN74LVC1G123DCUR | SN74LVC2G125DCUR |
|-----------------|------------------|------------------|
| SN74LVC1G06DCKR | SN74LVC1G125DBVR | SN74LVC2G125DCUT |
| SN74LVC1G07DCKR | SN74LVC1G125DBVT | SN74LVC2G132DCUR |

# **Qualification Report**

Approve Date 30-Oct-2019

### **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition       | Duration     | Qual Device:<br>LSF0102DCUR | Qual Device:<br>SN74LVC1G123DCUR |
|------|-----------------------------|--------------|-----------------------------|----------------------------------|
| PC   | PreCon Level 1              | Level 1-260C | 3/231/0                     | 3/231/0                          |
| HAST | Biased HAST, 130C/85%RH     | 96 Hours     | 3/231/0                     | 3/231/0                          |
| AC   | Autoclave 121C              | 96 Hours     | 3/231/0                     | 3/231/0                          |
| TC   | Temperature Cycle, -65/150C | 500 Cycles   | 3/231/0                     | 3/231/0                          |
| HTSL | High Temp Storage Bake 170C | 420 Hours    | 3/231/0                     | 3/231/0                          |
| HTOL | Life Test, 125C             | 1000 Hours   | 3/231/0                     | 3/231/0                          |
| LI   | Lead Fatigue                | Leads        | 3/66/0                      | -                                |
| LI   | Lead Pull                   | Leads        | 3/18/0                      | -                                |
| MISC | Salt Atmosphere             | 24 Hours     | 3/66/0                      | -                                |
| SD   | Surface Mount Solderability | PB           | 3/66/0                      | -                                |
| SD   | Surface Mount Solderability | PB-Free      | 3/66/0                      | -                                |
| DS   | Die Shear                   |              | 3/30/0                      | 3/30/0                           |
| PKG  | PKG Lead Finish Adhesion    |              | 3/45/0                      | -                                |
| WBP  | Bond Pull                   | Wires        | 3/228/0                     | 3/228/0                          |

| Туре | Test Name / Condition      | Duration | Qual Device:<br>LSF0102DCUR | Qual Device:<br>SN74LVC1G123DCUR |
|------|----------------------------|----------|-----------------------------|----------------------------------|
| WBS  | Bond Shear                 | Wires    | 3/228/0                     | 3/228/0                          |
| FLAM | Flammability (IEC 695-2-2) |          | 3/15/0                      | -                                |
| FLAM | Flammability (UL 94V-0)    |          | 3/15/0                      | -                                |
| FLAM | Flammability (UL-1694)     |          | 3/15/0                      | -                                |

- QBS: Qual By Similarity
- Qual Device SN74LVC1G123DCUR is qualified at LEVEL1-260CG
- Qual Device LSF0102DCUR is qualified at LEVEL1-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

# **Qualification Report**

Approve Date 09-Jun-2017

#### **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Туре     | Test Name /<br>Condition            | Duratio<br>n | Qual Device:<br>SN74AHC1G14DBV<br>R | Qual Device:<br>SN74CBTLV1G125DBV<br>R | Qual Device:<br>SN74LVC1G17DBV<br>R | Qual Device:<br>TL431AIDBV<br>R | Qual Device:<br>TLVH431AIDBV<br>R |
|----------|-------------------------------------|--------------|-------------------------------------|--|-------------------------------------|---------------------------------|-----------------------------------|
| AC       | Autoclave<br>121C                   | 96 Hours     | 3/231/0                             | 3/231/0                                | 3/231/0                             | 2/154/0                         | 1/77/0                            |
| AC       | Autoclave<br>121C                   | 144<br>Hours | 3/231/0                             | 3/231/0                                | 3/231/0                             | 2/154/0                         | 1/77/0                            |
| FLA<br>M | Flammability<br>(IEC 695-2-2)       | J            | 3/15/0                              | 100.00                                 | -                                   | -                               | -                                 |
| FLA<br>M | Flammability<br>(UL 94V-0)          | 0)           | 3/15/0                              | <b>.</b>                               | -                                   | -                               | -                                 |
| FLA<br>M | Flammability<br>(UL-1694)           |              | 3/15/0                              | -                                      | -                                   | -                               | -                                 |
| HAS<br>T | Biased<br>HAST,<br>130C/85%R<br>H   | 96 Hours     | 3/231/0                             | 3/231/0                                | 3/231/0                             | 2/154/0                         | 1/77/0                            |
| HAS<br>T | Biased<br>HAST,<br>130C/85%R<br>H   | 192<br>Hours | 3/231/0                             | 3/231/0                                | 3/231/0                             | 2/154/0                         | 1/77/0                            |
| HTO<br>L | Life Test,<br>150C                  | 300<br>Hours | 3/231/0                             | 3/231/0                                | 3/231/0                             | 2/154/0                         | 1/77/0                            |
| HTSL     | High Temp.<br>Storage<br>Bake, 170C | 400<br>Hours | 3/231/0                             | 3/231/0                                | 3/231/0                             | 2/154/0                         | 1/77/0                            |

| HTSL | High Temp.<br>Storage<br>Bake, 170C | 600<br>Hours    | 3/231/0 | 3/231/0 | 3/231/0 | 2/154/0 | 1/77/0 |
|------|-------------------------------------|-----------------|---------|---------|---------|---------|--------|
| LI   | Lead Fatigue                        | Leads           | 3/66/0  | -       | -       | 2/44/0  | 1/22/0 |
| LFA  | Lead Finish<br>Adhesion             | Leads           | 3/45/0  | -       | -       | 2/30/0  | 1/15/0 |
| LI   | Lead Pull to<br>Destruction         | Leads           | 3/66/0  | -       | - 6     | 2/44/0  | 1/22/0 |
| PD   | Physical<br>Dimensions              |                 | 3/15/0  | -       |         | 2/10/0  | 1/5/0  |
| SD   | Solderability                       | Pb              | 3/66/0  | -       | 100     | 2/44/0  | 1/22/0 |
| SD   | Solderability                       | Pb Free         | 3/66/0  | -       | 0,40    | 2/44/0  | 1/22/0 |
| TC   | Temperature<br>Cycle, -<br>65/150C  | 500<br>Cycles   | 3/231/0 | 3/231/0 | 3/231/0 | 2/154/0 | 1/77/0 |
| TC   | Temperature<br>Cycle, -<br>65/150C  | 750<br>Cycles   | 3/231/0 | 3/231/0 | 3/231/0 | 2/154/0 | 1/77/0 |
| DSS  | Die Shear                           | Die             | 3/30/0  | 3/30/0  | 3/30/0  | 2/20/0  | 1/10/0 |
| WBP  | Bond Pull                           | Wires           | 3/228/0 | 3/228/0 | 3/228/0 | 2/152/0 | 1/76/0 |
| WBS  | Ball Bond<br>Shear                  | Wires           | 3/228/0 | 3/228/0 | 3/228/0 | 2/152/0 | 1/76/0 |
| MSL  | Moisture<br>Sensitivity<br>Level    | 1-260C          | 3/36/0  | 0.00    |         | 2/24/0  | 1/12/0 |
| SA   | Salt<br>Atmosphere                  | 24 Hours        | 3/66/0  | 10 -5   |         | -       | -      |
| XR   | X-Ray                               | (top side only) | 3/15/0  | 3/15/0  | 3/15/0  | 2/10/0  | 1/5/0  |

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

| Location     | E-Mail                         |
|--------------|--------------------------------|
| USA          | PCNAmericasContact@list.ti.com |
| Europe       | PCNEuropeContact@list.ti.com   |
| Asia Pacific | PCNAsiaContact@list.ti.com     |
| WW PCN Team  | PCN www admin_team@list.ti.com |

<sup>-</sup> Qual Device SN74AHC1G14DBVR is qualified at LEVEL1-260C

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